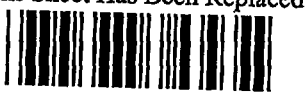
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ABSTRACT OF THE DISCLOSURE

A semiconductor apparatus includes a thin film belt-like insulating tape having a plurality of predetermined wire patterns thereon, and a plurality of IC chips that are provided on a surface of the insulating tape at uniform spaces in a lengthwise direction and electrically connected with the wire patterns, and further includes thick film reinforcing tapes with sprocket holes for transport use provided at uniform spaces, the reinforcing tapes being provided on both side portions of the insulating tape, in the lengthwise direction.

Figure 1

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